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To the Honorable Commissioner of Patents

101346563

Send original documents or copy thereof.

1 Name of conveying party(ies):

Chia-Yung Chiu



2 Name and address of receiving party(ies):

Taiwan Semiconductor Manufacturing Co. Ltd.  
No. 121 Park Avenue 3  
Science-Based Industrial Park  
Hsin-Chu, Taiwan, R.O.C.

Additional name(s) & address(es) attached  Yes  No

3 Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other:

Execution Date: February 2, 2000

4 Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No(s).

09/499,606

B. Patent No(s)

Additional numbers attached?  Yes  No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG  
Tung & Associates  
838 W. Long Lake Road  
Suite 120  
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:

1

7 Total fee (37 CFR 3.41)

\$40.00

- Enclosed
- Authorized to be charged to deposit account

8 Deposit Account Number: 50-0484

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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung  
Name of Person Signing  
Registration No. 31,311

Signature

April 25, 2000

Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

**ASSIGNMENT**

WHEREAS, I, CHIA-YUNG CHIU have invented certain improvements in METHOD AND APPARATUS FOR PREVENTING ARCING IN SPUTTER CHAMBER for which an application for a United States Patent was filed on February 7, 2000, Application Serial No. 09/499,606; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I, CHIA-YUNG CHIU, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by me on the 2nd day of February, 2000, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of

said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

I further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and I further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

CHIA-YUNG CHIU  
CHIA-YUNG CHIU

**TUNG & ASSOCIATES**  
**838 W. Long Lake Road**  
**Suite 120**  
**Bloomfield Hills, Michigan 48302**